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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/706,468	11/12/2003	Sung Jin Yang	AMKOR-095A	6744	
7663	7590 07/13/2006		EXAMINER		
	BRUNDA GARRED & B	TRINH, HOA B			
	RISE, SUITE 250 O, CA 92656	ART UNIT	PAPER NUMBER		
	•		2814		
			DATE MAILED: 07/13/2000	5	

Please find below and/or attached an Office communication concerning this application or proceeding.

	•	App	ication No.	Applicant(s)				
Office Action Summary		10/7	06,468	YANG ET AL.				
		Exar	niner	Art Unit				
		Vikki	H. Trinh	2814				
Period fo	The MAILING DATE of this commun or Reply	ication appears o	n the cover sheet	with the correspondence ad	idress			
WHIC - Exter after - If NC - Failu Any	ORTENED STATUTORY PERIOD F CHEVER IS LONGER, FROM THE M resions of time may be available under the provisions SIX (6) MONTHS from the mailing date of this comm reprived for reply is specified above, the maximum st re to reply within the set or extended period for reply reply received by the Office later than three months a red patent term adjustment. See 37 CFR 1.704(b).	IAILING DATE C of 37 CFR 1.136(a). In nunication. atutory period will apply will, by statute, cause t	OF THIS COMMUN no event, however, may and will expire SIX (6) Mo the application to become	NICATION. a reply be timely filed ONTHS from the mailing date of this c ABANDONED (35 U.S.C. § 133).	,			
Status								
1) 又	Responsive to communication(s) file	ed on 12 Novemb	per 2003.					
•	· · · · · · · · · · · · · · · · · · ·		This action is non-final.					
3)	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is							
,	closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Disposit	ion of Claims							
4)⊠ Claim(s) <u>1-24</u> is/are pending in the application.								
	4a) Of the above claim(s) is/are withdrawn from consideration.							
5)	5) Claim(s) is/are allowed.							
6)⊠	Claim(s) <u>1-24</u> is/are rejected.							
7)	Claim(s) is/are objected to.							
8) 🗌	8) Claim(s) are subject to restriction and/or election requirement.							
Applicat	ion Papers							
9) 🗌	The specification is objected to by th	e Examiner.						
10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.								
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).								
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).								
11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.								
Priority (under 35 U.S.C. § 119			×				
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 								
2) Notice	te of References Cited (PTO-892) se of Draftsperson's Patent Drawing Review (F mation Disclosure Statement(s) (PTO-1449 or		Paper N 5) Notice o	v Summary (PTO-413) o(s)/Mail Date If Informal Patent Application (PT	, (O-152)			
	r No(s)/Mail Date <u>03/12,15, 21/2004</u> .	0.00.00)	6) Other: _		•			

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1-24 are rejected under 35 U.S.C. 102(b) as being anticipated by Takemura et al. (EP 1032037, applicant cited) (hereinafter Takemura).

As to claim 1, Takemura discloses a semiconductor package, comprising a die paddle 2, 2a (fig. 1) defining multiple corners and opposed first and second surfaces; at least one set of leads 1 or 3 (fig. 1b) extending at least partially about the die paddle in spaced relation thereto, each of the leads having opposed first and second surfaces; at least one tie bar 12, 13, 2b, 9 (fig. 1) attached to and extending from one of the corners of the die paddle 2a, the tie bar having opposed first and second surfaces and at least one aperture (fig. 1 and fig. 1b, area between 2b and 9) disposed therein and extending between the first and second surfaces thereof; a semiconductor die 4 (fig. 1) attached to the first surface of the die paddle 2a and electrically connected to at least one of the leads 3; and a package body 6 at least partially covering the die paddle, the leads, the tie bar, and the semiconductor die such that the second surfaces of the leads 3, 1 (fig. 1) are exposed in a common exterior surface of the package body 6, and a portion of the package body 6 extends through the aperture of the tie bar (fig. 1).

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As to claims 2, 16, the die paddle 2, 2a (fig. 1b) has a quadrangular configuration defining four corners; and four tie bars 3 are attached to and extend diagonally from respective ones of the four corners of die paddle 2(fig. 1b).

As to claim 3, each of the tie bars 3 defines an outer end surface; and the at least one aperture (fig. 1b) of each of the tie bars is disposed in close proximity to the outer end surface thereof.

As to claim 4, the package body 6 (fig. 1a) defines four chamfers; and the outer end surface of each of the tie bars extends to a respective one of the chamfers (fig. 1b).

As to claim 5, each of the tie bars 3 includes a plurality of apertures (fig. 1b) disposed therein; portions of the package body extend through each of the apertures of each of the tie bars; and one of the apertures of each of the tie bars is disposed in close proximity to the outer end surface thereof.

As to claim 6, the first and second surfaces of the die paddle 2a (fig. 1b) are each generally planar; the die paddle 2a includes an etched surface which circumvents the second surface thereof; the first and second surfaces of each of the tie bars 3 are each generally planar; the first surface of each of the tie bars extends in substantially co-planar relation to the first surface of the die paddle 2a; and the second surface of each relation to the etched surface of the die paddle 2a.

As to claim 7, the first and second surfaces of each of the leads 1, 3 (fig. 1b) are each generally planar; the first surface of each of the leads 1, 3 (fig. 1) extends in substantially co-planar relation to the first surface of the die paddle; the second surface of each of the leads 3 extends in substantially co-planar relation to the second surface of the die paddle

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2, 2a; and the second surfaces of the leads and the second surface of the die paddle are exposed in and substantially flush with the exterior surface of the package body (fig. 1, 1b).

As to claim 8, the leads 1, 3 (fig. 1) are arranged in an inner set which extends at least partially about the die paddle 2 in spaced relation thereto, and an outer set which extends at least partially about the inner set in spaced relation thereto.

As to claim 9, the leads 1, 3 (fig. 1b) of the inner set and the leads of the outer set are separated from each other by a plurality of isolation trenches formed in the exterior surface of the package body 6.

As to claim 10, the portions of each of the leads 1, 3 (fig. 1b)of the inner and outer sets are exposed in respective ones of the isolation trenches (fig. 1b).

As to claims 11 and 21, the leads 1, 3 (fig. 1b) are arranged in an inner set which extends at least at partially about the die paddle 2 in spaced relation thereto, and an outer set 1 or 3 (fig. 1b) which extends at least partially about the inner set in spaced relation thereto.

Note that lead 1 (fig. 1) is interpreted to have an inner portion 2b separated by a trench or aperture from the outer portion 9 (fig. 1)

As to claims 12 and 22, the leads 1, 3 (fig. 1b) of the inner set and the leads of the outer set are separated from each other by a plurality of isolation trenches formed in the exterior surface of the package body. Note that lead 1 (fig. 1) is interpreted to have an inner portion 2b separated by a trench or aperture from the outer portion 9 (fig. 1)

As to claims 13 and 23, portions of each of the leads 1 or 3 (fig. 1) of the inner and outer sets are exposed in respective ones of the isolation trenches. Note for example that lead 1

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(fig. 1) is interpreted to have an inner portion 2b separated by a trench or aperture from the outer portion 9 (fig. 1)

As to claims 14 and 24, the semiconductor die 4 is electrically connected to the first surfaces of the leads 1 via conductive wires 5 (fig. 1) which are covered by the package body 6.

As to claim 15, the aperture 12 (fig. 1b) of the tie bar 3 has a circular configuration.

As to claim 17, each of the recesses (fig. 1) defines first and second recess walls 13, 14; and portions of the outer end surface of each of the tie bars 3 are exposed in each of the first and second recess walls 13, 14 of a respective one of the recesses (fig. 1).

As to claim 18, the first and second recess walls 13, 14 (fig. 1) of each of the recesses extend in generally perpendicular relation to each other (fig. 1b).

As to claim 19, the die paddle 2, 2a (fig. 1 and fig. 1b) includes an etched surface which circumvents the second surface thereof; the first surface of each of the tie bars 3 extends in substantially co-planar relation to the first surface of the die paddle 2a; and the second surface of each of the tie bars 3 extends in substantially co-planar relation to the etched surface of the die paddle 2.

As to claim 20, the first surface of each of the leads 1 or 3 (fig. 1) extends in substantially co-planar relation to the first surface of the die paddle 2; the second surface of each of the leads 1 or 3 extends in substantially co-planar relation to the second surface of the die paddle 2, 2a; and the second surfaces of the leads 1 or 3 and the second surface of the die paddle 2, 2a are exposed in and substantially flush with the exterior surface of the package body (fig. 1).

Conclusion

3. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

4. Cheng et al. (2003/0168719) discloses a leadframe having a die 30, a die paddle 22, inner lead 32 and outer lead 34. See fig. 2.

Any inquiry concerning this communication or earlier communications from the Examiner should be directed to Vikki Trinh whose telephone number is (571) 272-1719. The Examiner can normally be reached from Monday-Friday, 9:00 AM - 5:30 PM Eastern Time. If attempts to reach the examiner by telephone are unsuccessful, the Examiner's supervisor, Mr. Wael Fahmy, can be reached at (571) 272-1705. The office fax number is 703-872-9306.

Any request for information regarding to the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Also, status information for published applications may be obtained from either Private PAIR or Public Pair. In addition, status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. If you have questions pertaining to the Private PAIR system, please contact the Electronic Business Center (EBC) at 866-217-9197 (toll free).

Lastly, paper copies of cited U.S. patents and U.S. patent application publications will cease to be mailed to applicants with Office actions as of June 2004. Paper copies of foreign patents and non-patent literature will continue to be included with office actions. These cited U.S. patents and patent application publications are available for download via the Office's PAIR. As an alternate source, all U.S. patents and patent application publications are available on the USPTO web site (www.uspto.gov), from the Office of Public Records and from

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commercial sources. Applicants are referred to the Electronic Business Center (EBC) at http://www.uspto.gov/ebc/index.html or 1-866-217-9197 for information on this policy. Requests to restart a period for response due to a missing U.S. patent or patent application publications will not be granted.

Vikki Trinh, Patent Examiner AU 2814

> HOWARD WEISS PRIMARY EXAMINER